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1752-2 1.1		Web Site for Informat://www.ipc.org/IPC-1	ırd		Form Type * Declaration Class * Class 6 - RoHS Yes/I					No, Homogeneous Materials and Mfg Informat					
Supplier Information															
Company Name * Company Unique ID				Unique ID Au	Response Date *				Response Document ID						
SEMTECH CORPORATION SEMTE		SEMTECH CORPOR	RATION												
Contact Name *		Title - Contact		Phone - Contact *		Email - Contact *				D	mlianta -	Cantast			anna ann tationa
Elvia Finkel		Inside Sales		805-498-2111		efinkel@semtech.com				Duplicate Contact -> Authorized Representative					
Authorized Representative *		Title - Representative		Phone - Representative *		Email - Representative *			*	Supplier Comments or URL for Additional Information					
Elvia Finkel		Inspector QA, Source		1-805-498-2111 X 2643		efinkel@semtech.com									
Requester Item Number		Mfr Item Number		Mfr Item Name	;	Effectiv	e Date	Version	n Manufacturing		te V	Weight *	UC	DM	Unit Type
		GS2961-IBE3		3Gb/s, HD, S	D SDI Receiver, v	V	Taiwa		Taiwar	wan		391.43	mç	3	Each
Alternate Recommend	ation					Alternat		Alternate	te Item Comments						•
Manufacturing Proce	ss In	formation													
Terminal Plating / Grid Array	Mater	ial	Terminal B	ase Alloy	J-STD-020 MSL Ra	ating	Peak Proc	ess Body	Temper	ature Max	x Time at I	Peak Tem	perature	Number	of Reflow Cycles
Tin/Silver/Copper (Sn/Ag/Cu) CU Alloy			1	3				260 C		30 sec		econds	3		
Comments GS2961-IBE3 is a REAC	H-cor	mpliant product, per	EU Regu	lation EC190	7/2006 to include	recent	addition	of SVH	C cand	idate list	t of subs	tances S	Septemb	er 2012	

Save the fields in Import fields from a Clear all of the Lock the fields on this **Export Data** Import Data Reset Form Lock Supplier Fields this form to a file file into this form fields on this form form to prevent changes **RoHS Material Composition Declaration Declaration Type *** Detailed Rohs Directive Rohs Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenvls (PBB). Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium 2002/95/EC Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a ?RoHS restricted substance?) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier?s liability and the Company?s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply. 1 - Item(s) does not contain RoHS restricted substances per the definition above Supplier Acceptance * Accepted **RoHS Declaration *** Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. **Declaration Signature**

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem	Item/SubItem		Homogeneous	Weight	Unit of		Level	Substance Category			Substance	CAS	Exempt	Weight	Oille Oi	Tolerance	ance	PPM
	Name		Material	Weight	Measure			Substance Category				UAS	Lxempt	Weight	Measure	-	+	
+1 -1	Substrate	+M -M	вт	159.84	mg	+C -C	Supplier		+S	-S	SiO2	7631-86-9		17.023	mg			106,50
									+S	-S	Acrylic	79-01-7		15.984	mg			1,000,0
									+S	-S	Ероху	7440-21-3		12.787	mg			80,000
									+S	-S	Bisphenol	80-05-7		23.976	mg			150,00
									+S	-S	Triazol	288-88-0		27.972	mg			175,00
									+S	-S	Cu	7440-50-85		58.821	mg			368,00
									+S	-S	Ni	7440-02 0		2.398	mg			15,000
									+S	-s	Au	7440-57-5		0.879	mg			5,500
+1 -1	Mold Compound	+M -M	KE-G1250	159.24	mg	+C -C	Supplier		+S	-S	Silica Fused	60676-86-0		140.131	mg			880,00
									+S	-S	Epoxy Resin	Trade Secre	•	9.554	mg			60,000
									+S	-S	Phenolic Resin	Trade Secre	•	8.758	mg			55,000
									+S	-S	Carbon Black	1333-86-4		0.796	mg			6,000
+1 -1	Chip 1	+M -M		12.54	mg	+C -C	Supplier		+S	-s	Si	7440-21-3		12.377	mg			987,00
									+S	-S	AI	7429-90-5		0.075	mg			6,000
									+S	-S	w	7440-33-7		0.05	mg			4,000
									+S	-S	Ti	7440-31-6		0.038	mg			3,000
+1 -1	Chip 2	+M -M		2.33	mg	+C -C	Supplier		+S	-S	Si	7440-21-3		2.323	mg			987,10
									+S	-S	AI	7429-90-5		0.003	mg			1,300
									+S	-S	w	7440-33-7		0.003	mg			1,240
									+S	-S	Ti	7440-31-6		0.001	mg			301
									+S	-s	Other			0	mg			59
+1 -1	Die Attach	+M -M	Ablestik 2100A	5.15	mg	+C -C	Supplier		+S	-s	Ag	7440-22-4		46,451	mg			955,00
									+S	-S	Epoxy Resin	900-36-5		0.335	mg			65,000

+S -S Functionalized Resin				ry 0.3	35 mg			65,000				
	+S -S Die	ester	Trade Se	cre 0.5	15 mg			100,00				
+l -l Wire	+M -M 25_NL03F	3.69 mg	+C -C Suppl	er		+S -S	Au		7440-57-5	3.69	mg	999,90
+I -I Solder Balls	+M -M Senju	48.64 mg	+C -C Suppl	er		+S -S	Sn		7440-31-5	46.451	mg	955,00
						+S -S	Ag		7440-22-4	1.946	mg	40,000
						+S -S	Cu		7440-31-5	0.243	mg	5,000